

PMP9700 REVA BOM

Designator	Quantity	Value	Description	Package	PartNumber	Mfr.
C1, C2, C3, C4	4	10uF	CAP, CERM, 10uF, 50V, +/-20%, X5R, 1210	1210	C3225X5R1H106M250AB	TDK
C6, C7, C18, C19	4	1uF	CAP, CERM, 1uF, 25V, +/-10%, X7R, 0603	0603	C1608X7R1E105K080AB	TDK
C8, C20, C21, C30, C31	5	1000pF	CAP, CERM, 1000pF, 50V, +/-5%, C0G/NP0, 0603	0603	C1608C0G1H102J	TDK
C9	1	0.1uF	CAP, CERM, 0.1uF, 50V, +/-10%, X7R, 0603	0603	06035C104KAT2A	AVX
C10	1	100pF	CAP, CERM, 100pF, 50V, +/-5%, C0G/NP0, 0603	0603	C1608C0G1H101J	TDK
C11	1	0.47uF	CAP, CERM, 0.47uF, 16V, +/-10%, X7R, 0603	0603	C0603C474K4RACTU	Kemet
C12, C13	2	0.1uF	CAP, CERM, 0.1uF, 50V, +/-10%, X7R, 0603	0603	C1608X7R1H104K	TDK
C16	1	220pF	CAP, CERM, 220pF, 50V, +/-5%, C0G/NP0, 0603	0603	C1608C0G1H221J	TDK
C17	1	0.033uF	CAP, CERM, 0.033uF, 50V, +/-10%, X7R, 0603	0603	GRM188R71H333KA61D	MuRata
C22, C26	2	390uF	CAP, OS-CON, 390uF, 20V, +/-20%, 0.014 ohm, 8x10 SMD	8x10	20SVPF390M	Sanyo
C23, C27	2	10uF	CAP, CERM, 10uF, 35V, +/-20%, X7R, 1206	1206	GMK325AB7106MM-T	Taiyo Yuden
C33, C34	2	2200pF	CAP, CERM, 2200pF, 50V, +/-10%, X7R, 0603	0603	C0603C222K5RAC	Kemet
D1, D2	2		Diode, Schottky, 60V, 1A, SOD-123F	SOD-123F	PMEG6010CEH	NXP
L1, L2	2	5.6uH	Inductor, Shielded, Composite, 5.6uH, 21.2A, 0.01 ohm, SMD	11.3x10x10mm	XAL1010-562MEB	Coilcraft
Q1, Q2, Q3, Q4	4		MOSFET, N-CH, 40V, 3.4 milliohm, SON 5x6mm	SON 5x6mm	CSD18503Q5A	Texas Instruments
R1	1	1.00	RES, 1.00 ohm, 1%, 0.1W, 0805	0805	CRCW08051R00FKEA	Vishay-Dale
R2	1	100k	RES, 100k ohm, 1%, 0.1W, 0603	0603	CRCW0603100KFKEA	Vishay-Dale
R3	1	6.65k	RES, 6.65k ohm, 1%, 0.1W, 0603	0603	CRCW06036K65FKEA	Vishay-Dale
R4	1	16.2k	RES, 16.2k ohm, 1%, 0.1W, 0603	0603	CRCW060316K2FKEA	Vishay-Dale
R7	1	20.0k	RES, 20.0k ohm, 1%, 0.1W, 0603	0603	CRCW060320K0FKEA	Vishay-Dale
R8	1	100	RES, 100 ohm, 1%, 0.1W, 0603	0603	CRCW0603100RFKEA	Vishay-Dale
R10	1	20.0k	RES, 20.0k ohm, 1%, 0.1W, 0603	0603	CRCW060320K0FKEA	Vishay-Dale
R11	1	1.13k	RES, 1.13k ohm, 1%, 0.1W, 0603	0603	CRCW06031K13FKEA	Vishay-Dale
R14, R15	2	66.5k	RES, 66.5k ohm, 1%, 0.1W, 0603	0603	CRCW060366K5FKEA	Vishay-Dale
R16, R17, R21, R22	4	0	RES, 0 ohm, 5%, 0.1W, 0603	0603	CRCW06030000Z0EA	Vishay-Dale
R18, R20	2	0.003	RES, 0.003 ohm, 1%, 0.5W, 2010	2010	WSL20103L000FEA	Vishay-Dale
R23, R24, R31, R32	4	100	RES, 100 ohm, 1%, 0.1W, 0603	0603	RC0603FR-07100RL	Yageo America
R25, R26	2	10	RES, 10 ohm, 5%, 0.5W, 2010	2010	CRCW201010R0JNEFHP	Vishay-Dale
R27, R28, R29, R30	4	2.2	RES, 2.2 ohm, 5%, 0.1W, 0603	0603	CRCW06032R20JNEA	Vishay-Dale
TP1, TP2, TP5, TP6, TP100, TP102, TP103	7	Red	Test Point, Multipurpose, Red, TH	Keystone5010	5010	Keystone
TP101	1	Black	Test Point, Multipurpose, Black, TH	Keystone5011	5011	Keystone
U1	1		LM25119/LM25119Q Wide Input Range Dual Synchronous Buck Controller, RTV0032A	RTV0032A	LM25119PSQ/NOPB	Texas Instruments

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